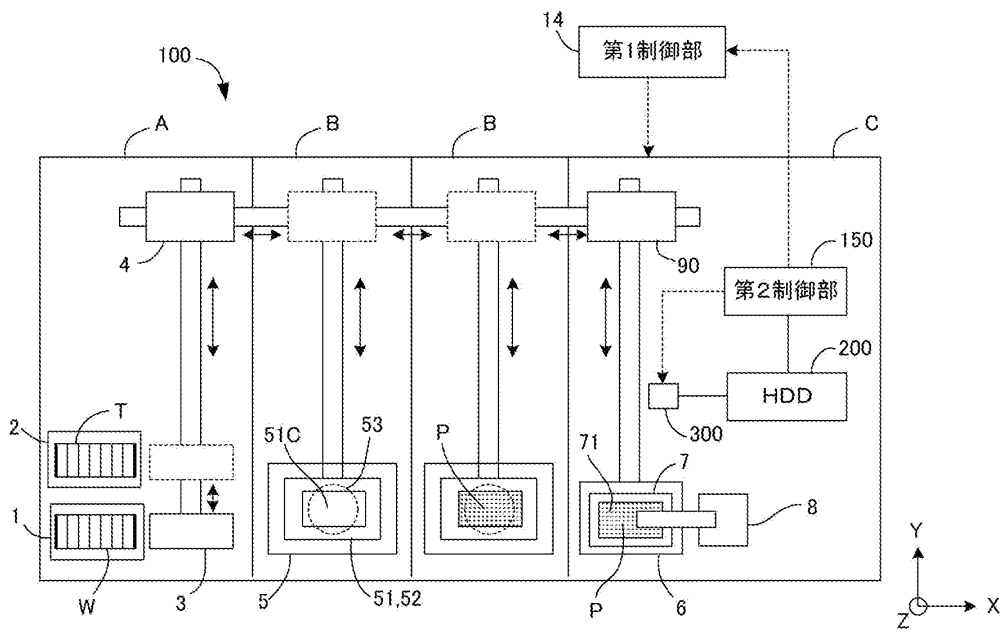
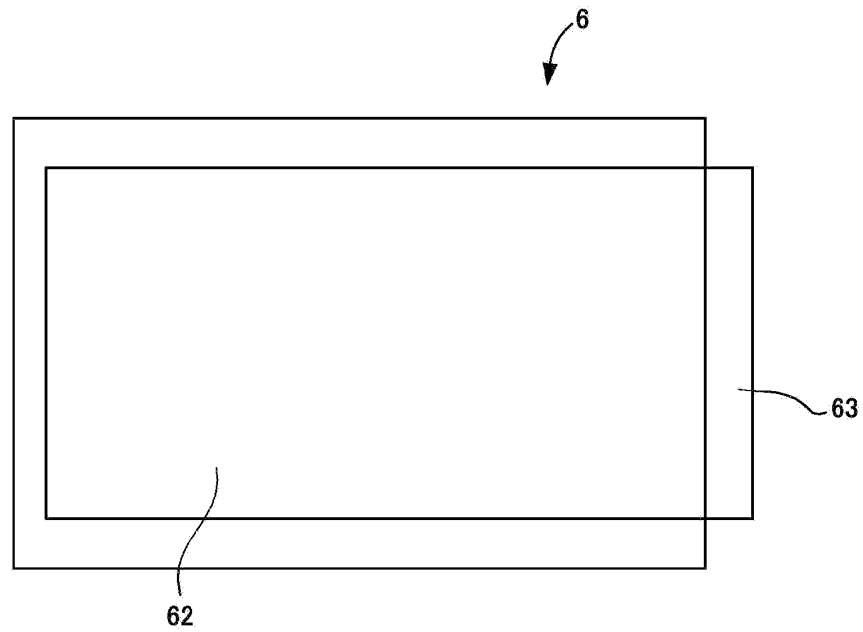


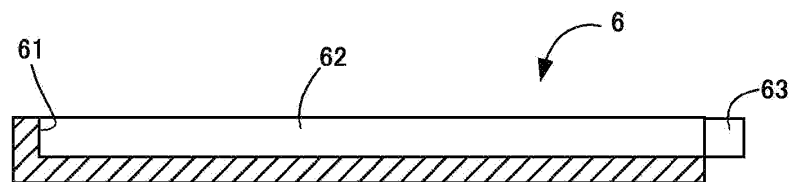
[図1]



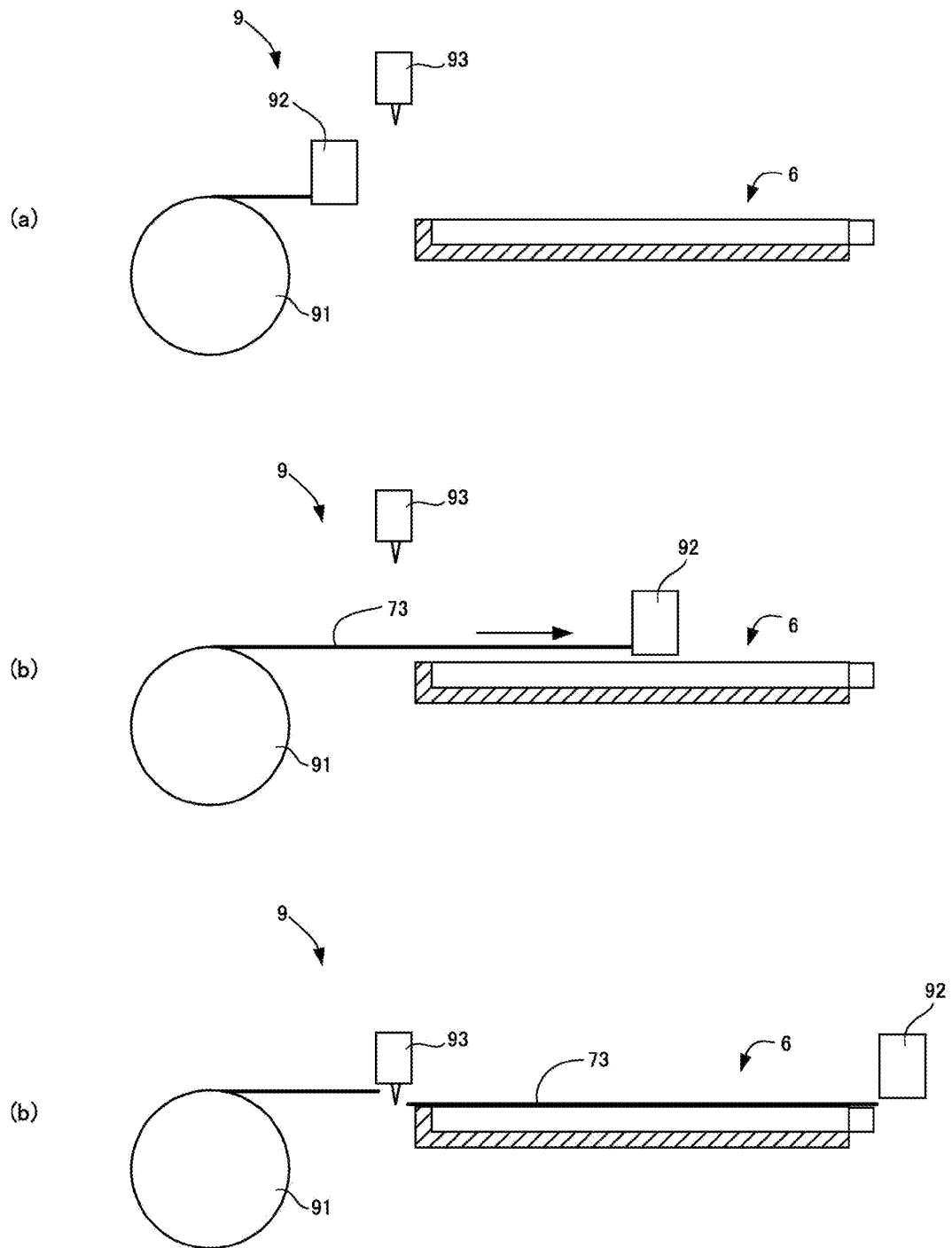
[図2]



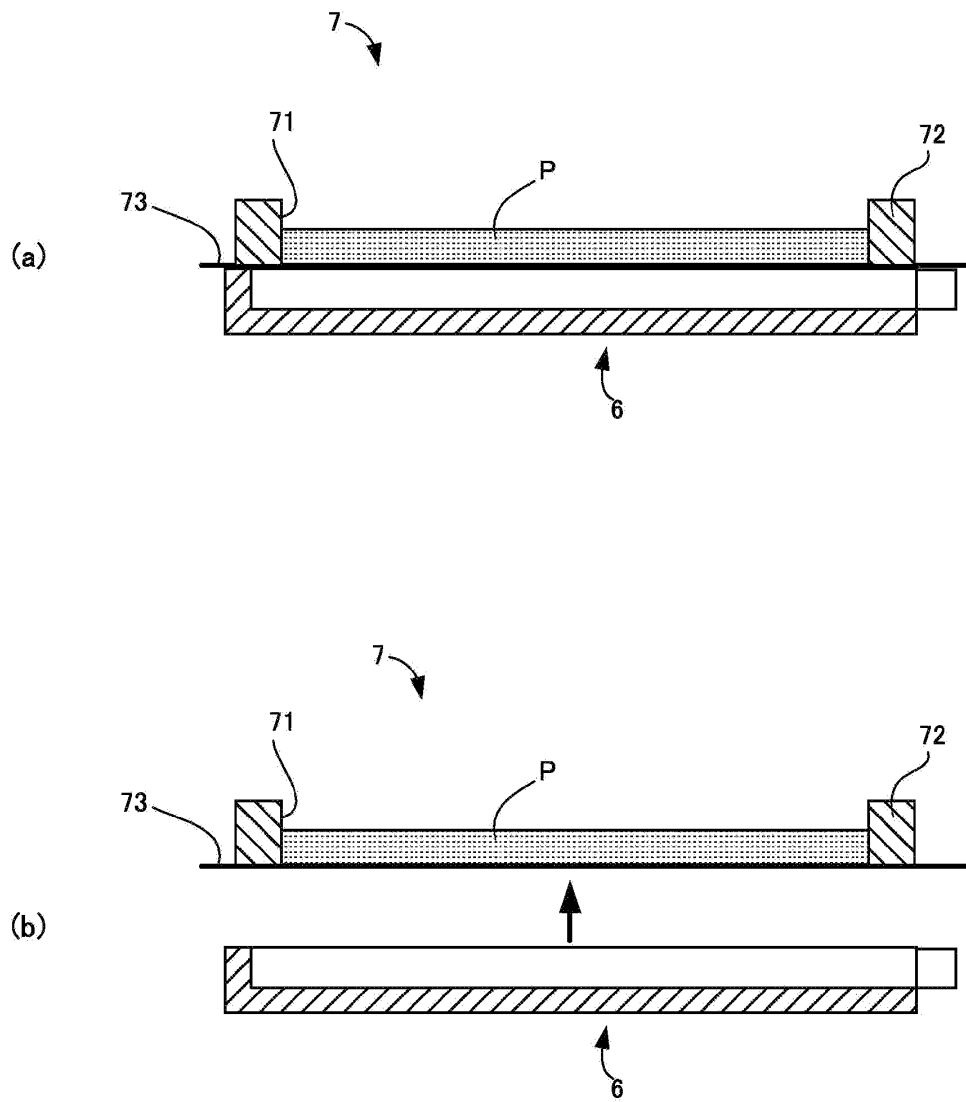
[図3]



[図4]

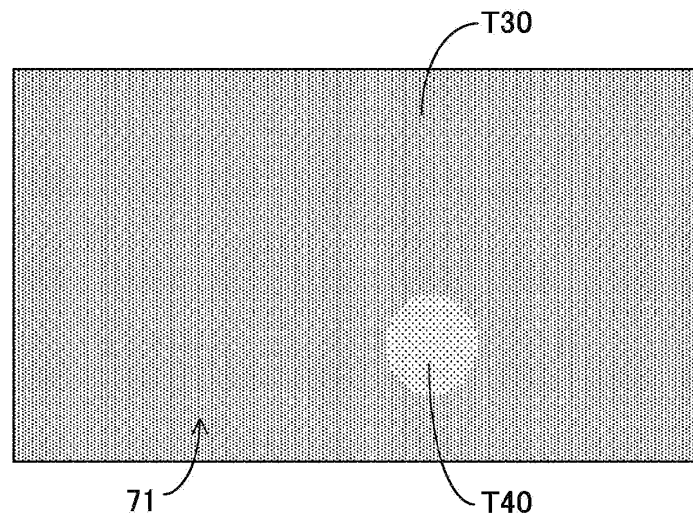


[図5]

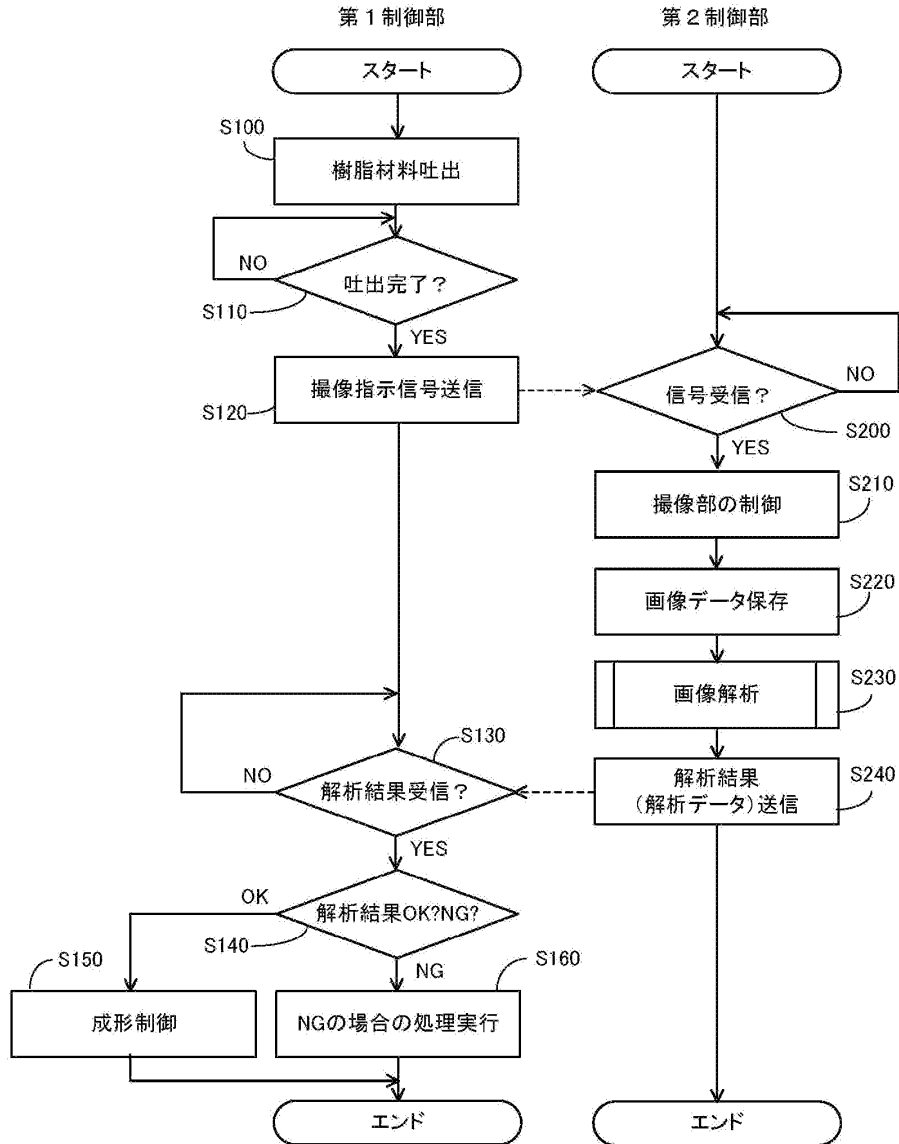


The diagram illustrates a cross-sectional view of a device assembly. At the bottom is a substrate 6. On top of the substrate is a layer 7. Layer 7 consists of two end regions, 71 and 72, which are hatched, and a central region P. Above layer 7 is a component 8, which is a rectangular block. There is a gap 12 between the top surface of layer 7 and the bottom surface of component 8. To the right of component 8 is a vertical rectangular block 11. A shaded region P is located between component 8 and block 11. Below block 11 is another rectangular block 16. A horizontal double-headed arrow indicates movement or interaction between block 11 and block 16. To the right of block 16 is a box labeled "第1制御部" (First Control Unit) 14. Dashed arrows connect the "第1制御部" 14 to block 11 and block 16.

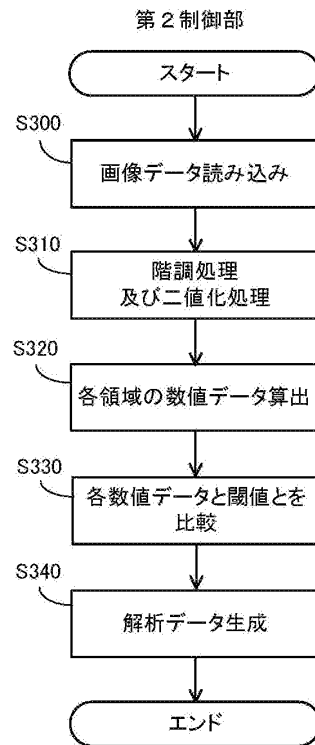
[図8]



[図9]



【図10】



【図11】

T1	T2	T3	T4	T5	T6
T7	T8	T9	T10	T11	T12
T13	T14	T15	T16	T17	T18

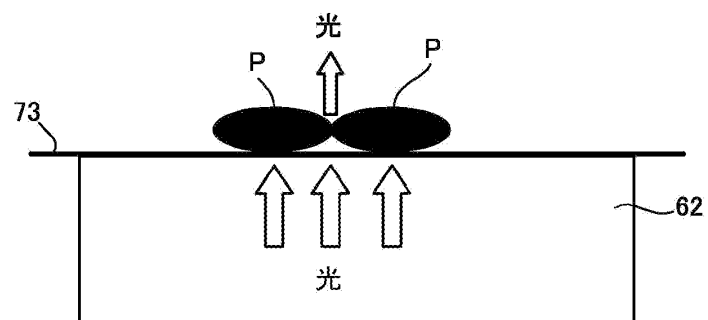
71 ↗

[図12]

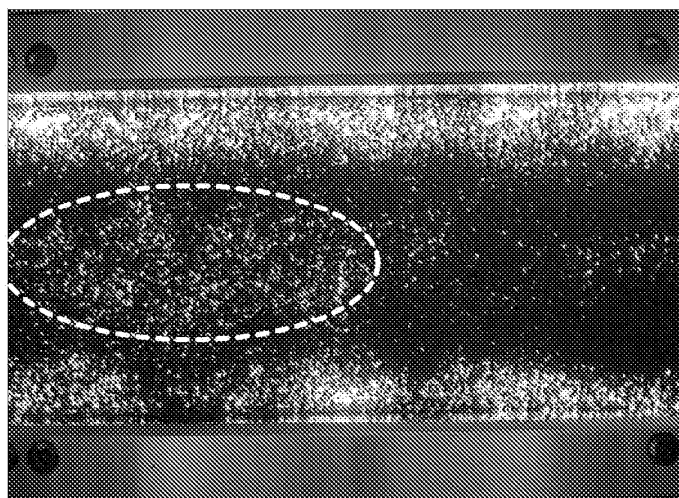
領域	OK/NG	白の数
T1	OK	Z1
T2	NG	Z2
...	...	...
T17	NG	Z17
T18	OK	Z18

↑
D1

[図13]



[図14]



[図15]

